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02/05/02

U.S. UTILITY Patent Application

PATENT NUMBER and  
ISSUE DATE

|                      |                           |              |               |             |                    |
|----------------------|---------------------------|--------------|---------------|-------------|--------------------|
| APPL NUM<br>10062505 | FILING DATE<br>02/05/2002 | CLASS<br>438 | SUBCLASS<br>7 | GAU<br>2812 | EXAMINER<br>SE IER |
|----------------------|---------------------------|--------------|---------------|-------------|--------------------|

\*\*APPLICANTS: Kawano Hiroyuki;

\*\*CONTINUING DATA VERIFIED:

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\*\* FOREIGN APPLICATIONS VERIFIED:  
JAPAN 2001-065884 03/09/2001

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no  
35 USC 119 conditions met ☐ yes ☐ no

ATTORNEY DOCKET NO

OKI.304

Verified and Acknowledged Examiners's initials  
TITLE : Method of manufacturing a semiconductor device including etching of a peripheral area before  
chemical-mechanical polishing

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED

ISSUE FEE

Amount Due Date Paid

☐ TERMINAL  
DISCLAIMER

Assistant Examiner

Primary Examiner

PREPARED FOR ISSUE

CLAIMS ALLOWED

Total Claims

Print Claim for  
O.G.

DRAWING

Sheets Drwg.

Figs.Drwg.

Print Fig.

Application Examiner

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